

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :  
Hidenao SUZUKI et al. : **Attn: APPLICATION BRANCH**  
Serial No. NEW : Attorney Docket No. 2004\_0147A  
Filed January 30, 2004 :  
ELECTROLYTIC PROCESSING APPARATUS  
AND SUBSTRATE PROCESSING APPARATUS :  
THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

**COVER LETTER ACCOMPANYING APPLICATION FILED WITHOUT EXECUTED  
DECLARATION UNDER 37 CFR 1.53(b) AND IN A LANGUAGE  
OTHER THAN ENGLISH UNDER 37 CFR 1.52(d)**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Enclosed is a new patent application entitled "ELECTROLYTIC PROCESSING APPARATUS AND SUBSTRATE PROCESSING APPARATUS". This application is submitted in the Japanese language under the provisions of 37 CFR 1.52(d).

Furthermore, the present application is submitted under the provisions of 37 CFR 1.53(b), and the application as filed does not include an executed declaration. However, accompanying the application is an unexecuted declaration listing the inventor information.

The application as filed further does not include an executed power of attorney, and accordingly, it is requested that communication initially be directed to the following firm, until an executed power of attorney and declaration are filed:

WENDEROTH, LIND & PONACK, L.L.P.  
2033 K Street, N.W., Suite 800  
Washington, D.C. 20006-1021

Telephone: (202) 721-8200  
Facsimile: (202) 721-8250

The required filing fee of \$770.00 is enclosed.

Respectfully submitted,

Hidenao SUZUKI et al.

By   
Michael S. Huppert  
Registration No. 40,268  
Attorney for Applicants

MSH/kjf  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
January 30, 2004

## DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original    () Supplemental    () Substitute    () PCT    () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: ELECTROLYTIC PROCESSING APPARATUS AND SUBSTRATE PROCESSING APPARATUS

of which is described and claimed in:

( the attached specification, or  
 ( the specification in application Serial No. \_\_\_\_\_, filed January 30, 2004, and with amendments through \_\_\_\_\_, or  
 ( the specification in International Application No. , filed , and as amended on (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2003-25159	January 31, 2003	YES
Japan	2003-384322	November 13, 2003	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from WATANABE & HOTTA as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Direct Correspondence to:		Direct Telephone Calls to:	
<b>CUSTOMER NO.</b> <b>000513</b>		<b>WENDEROTH, LIND &amp; PONACK, L.L.P.</b> 2033 "K" Street, N.W., Suite 800 Washington, D.C. 20006-1021  Phone:(202) 721-8200 Fax:(202) 721-8250	
<b>Full Name of First Inventor</b>	<b>FAMILY NAME</b> SUZUKI	<b>FIRST GIVEN NAME</b> Hidenao	<b>SECOND GIVEN NAME</b>
<b>Residence &amp; Citizenship</b>	<b>CITY</b> Tokyo	<b>STATE OR COUNTRY</b> Japan	<b>COUNTRY OF CITIZENSHIP</b> Japan
<b>Post Office Address</b>	<b>ADDRESS</b> c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	<b>CITY</b>	<b>STATE OR COUNTRY</b> ZIP CODE
<b>Full Name of Second Inventor</b>	<b>FAMILY NAME</b> NOMURA	<b>FIRST GIVEN NAME</b> Kazufumi	<b>SECOND GIVEN NAME</b>
<b>Residence &amp; Citizenship</b>	<b>CITY</b> Tokyo	<b>STATE OR COUNTRY</b> Japan	<b>COUNTRY OF CITIZENSHIP</b> Japan
<b>Post Office Address</b>	<b>ADDRESS</b> c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	<b>CITY</b>	<b>STATE OR COUNTRY</b> ZIP CODE
<b>Full Name of Third Inventor</b>	<b>FAMILY NAME</b> IDE	<b>FIRST GIVEN NAME</b> Kunihitto	<b>SECOND GIVEN NAME</b>
<b>Residence &amp; Citizenship</b>	<b>CITY</b> Tokyo	<b>STATE OR COUNTRY</b> Japan	<b>COUNTRY OF CITIZENSHIP</b> Japan
<b>Post Office Address</b>	<b>ADDRESS</b> c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	<b>CITY</b>	<b>STATE OR COUNTRY</b> ZIP CODE
<b>Full Name of Fourth Inventor</b>	<b>FAMILY NAME</b> KANDA	<b>FIRST GIVEN NAME</b> Hiroyuki	<b>SECOND GIVEN NAME</b>
<b>Residence &amp; Citizenship</b>	<b>CITY</b> Tokyo	<b>STATE OR COUNTRY</b> Japan	<b>COUNTRY OF CITIZENSHIP</b> Japan
<b>Post Office Address</b>	<b>ADDRESS</b> c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	<b>CITY</b>	<b>STATE OR COUNTRY</b> ZIP CODE
<b>Full Name of Fifth Inventor</b>	<b>FAMILY NAME</b> MISHIMA	<b>FIRST GIVEN NAME</b> Koji	<b>SECOND GIVEN NAME</b>
<b>Residence &amp; Citizenship</b>	<b>CITY</b> Tokyo	<b>STATE OR COUNTRY</b> Japan	<b>COUNTRY OF CITIZENSHIP</b> Japan
<b>Post Office Address</b>	<b>ADDRESS</b> c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	<b>CITY</b>	<b>STATE OR COUNTRY</b> ZIP CODE

Full Name of Sixth Inventor	FAMILY NAME MIHARA	FIRST GIVEN NAME Naoki	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Seventh Inventor	FAMILY NAME MAKINO	FIRST GIVEN NAME Natsuki	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Eighth Inventor	FAMILY NAME KATSUOKA	FIRST GIVEN NAME Seiji	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS c/o Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo, Japan	CITY	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Hideano SUZUKI

2nd Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Kazufumi NOMURA

3rd Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Kunihito IDE

4th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Hiroyuki KANDA

5th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Koji MISHIMA

6th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Naoki MIHARA

7th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Natsuki MAKINO

8th Inventor \_\_\_\_\_ Date \_\_\_\_\_  
 Seiji KATSUOKA

The above application may be more particularly identified as follows:

U.S. Application Serial No. \_\_\_\_\_ Filing Date January 30, 2004

Applicant Reference Number GEB2160-US Atty Docket No. 2004-0147A

Title of Invention ELECTROLYTIC PROCESSING APPARATUS AND SUBSTRATE PROCESSING APPARATUS